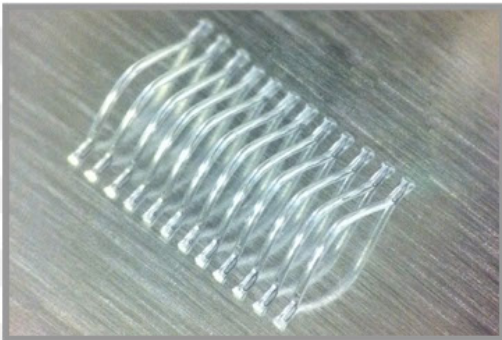




HB30 Heavy Wire Bonder

Motorized Z- & Y- Axis



- + 100 μ to 500 μ Aluminium Wire
- + 6,5" TFT Touch Screen
- + 100 Program Storage Capacities
- + Built in Dual Fiber Optic illuminator
- + Motorised Z Bond Head
- + Motorized Y travel for Step-Back loop control
- + 6:1 ratio X-Y manipulator
- + Loop Profile Programmable
- + Stitch bonding
- + Semi-auto, Step and Manual Bonding Mode

HB30 Heavy Wire Bonder

The HB30 is a **bench top size wire bonder**, ideal for laboratories, pilot and pre-production runs and small scale production lines. Easy operation with **TFT Touch Screen Operator System**. Direct access and simple adjustment to all bond parameters and programs.

Technical Spezifikationen

Ultrasonic system	PLL US System
Ultrasonic power	50 Watt Output
Bond time	0 - 10 sec.
Bond force	50 - 1500 cN

Aluminium wire diameter	100 to 500µm
Ribbon size max.	300 x 2000µm
Wire termination	Front Cut
Wire feed angle	90°
Motorized Y travel	Stepback up to 17 mm
Motorized Z travel	20 mm
Fine Table motion	15 mm
Mouse ratio	6:1 (Option 3:1)

Electrical Requirements	100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions	680 mm (27")W x 640 mm (25") D x 490 mm (19") H
Weight	Net 50 kg
Industry Standards	CE Standards

Specifications are subject to change without prior notice

Accessories:



Spotlight tagetting system



Workstage



Manual Z



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